

METHOD AND DEVICE OF PEELING SEMICONDUCTOR DEVICE USING
ANNULAR CONTACT MEMBERS

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ABSTRACT OF THE DISCLOSURE

10 In a semiconductor device manufacturing process, a
semiconductor wafer is diced into a plurality of
semiconductor chips, which are then peeled, from a dicing
tape, using a peeling device. The peeling device
includes a plurality of annular contact members arranged
one after another from the outside to the inside, and the
15 annular contact members are operated so that the
semiconductor chip is successively peeled from the tape
from the outer circumferential portion thereof toward the
central portion thereof.

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